

Title (en)
METHOD FOR PRODUCING A PRINTED CIRCUIT BOARD CONSISTING OF AT LEAST TWO PRINTED CIRCUIT BOARD REGIONS, AND PRINTED CIRCUIT BOARD

Title (de)
VERFAHREN ZUM HERSTELLEN EINER AUS WENIGSTENS ZWEI LEITERPLATTENBREICHEN BESTEHENDEN LEITERPLATTE SOWIE LEITERPLATTE

Title (fr)
PROCÉDÉ DE FABRICATION D'UNE CARTE DE CIRCUITS IMPRIMÉS CONSTITUÉE D'AU MOINS DEUX RÉGIONS AINSI QUE CARTE DE CIRCUITS IMPRIMÉS

Publication
EP 2452546 A1 20120516 (DE)

Application
EP 10743002 A 20100709

Priority
• AT 2010000254 W 20100709
• AT 4322009 U 20090710

Abstract (en)
[origin: WO2011003123A1] In a method for producing a printed circuit board consisting of at least two printed circuit board regions, wherein the printed circuit board regions each comprise at least one conductive layer and/or at least one device or one conductive component, wherein printed circuit board regions (20, 21, 22) to be connected to one another, in the region of in each case at least one lateral surface directly adjoining one another, are connected to one another by a coupling or connection, and wherein, after a coupling or connection of printed circuit board regions (20, 21, 22) to be connected to one another, at least one additional layer or ply of the printed circuit board is arranged or applied over the printed circuit board regions (20, 21, 22) to be connected to one another, it is provided that the additional layer is embodied as a conductive layer (26), which is contact-connected via plated-through holes (23) to conductive layers or devices or components integrated in the printed circuit board regions (20, 21, 22) to be connected to one another, as a result of which a simple and reliable connection or coupling of printed circuit board regions (20, 21, 22) to be connected to one another can be made available. Furthermore, a printed circuit board consisting of a plurality of printed circuit board regions (20, 21, 22) is made available.

IPC 8 full level
H05K 1/14 (2006.01); **H05K 1/18** (2006.01); **H05K 3/00** (2006.01); **H05K 3/36** (2006.01); **H05K 5/00** (2006.01)

CPC (source: EP KR US)
H05K 1/115 (2013.01 - US); **H05K 1/14** (2013.01 - KR); **H05K 1/142** (2013.01 - EP US); **H05K 1/18** (2013.01 - KR); **H05K 1/185** (2013.01 - EP US); **H05K 1/189** (2013.01 - US); **H05K 3/36** (2013.01 - KR); **H05K 3/368** (2013.01 - EP US); **H05K 3/46** (2013.01 - KR); **H05K 3/4691** (2013.01 - EP US); **H05K 3/4694** (2013.01 - EP US); **H05K 3/225** (2013.01 - EP US); **H05K 2201/0187** (2013.01 - EP US); **H05K 2201/09163** (2013.01 - EP US); **H05K 2201/09845** (2013.01 - EP US); **H05K 2203/1461** (2013.01 - EP US); **Y10T 29/49155** (2015.01 - EP US)

Citation (search report)
See references of WO 2011003123A1

Citation (examination)
• EP 1734580 A2 20061220 - NGK SPARK PLUG CO [JP]
• ES 2168070 A1 20020516 - LEAR AUTOMOTIVE EEDS SPAIN [ES]

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